

TL-01
0.0,0.0

TR-01
1920.0,0.0

TO EXTERNAL GRID AC INPUT (415V/480V)

TO 800 VDC BACKBONE BUS

SYSTEM INTERCONNECT 1 [CYAN]

SYSTEM INTERCONNECT 2 [GREEN]

FEED TO PRIMARY SUBSTATION

HIGH-EFFICIENCY RECTIFIER LINK

THE GRID-TO-CHIP ODYSSEY: ARCHITECTING THE 800 VDC AI FACTORY

END-TO-END POWER DISTRIBUTION FOR NVIDIA KYBER
AND NEXT-GENERATION 1MW RACK INFRASTRUCTURES

SYSTEM INTERCONNECT 1 [CYAN]

SYSTEM INTERCONNECT 2 [GREEN]

GRID SYNCHRONIZATION POINT

DIRECT DC DISTRIBUTION PATHWAY

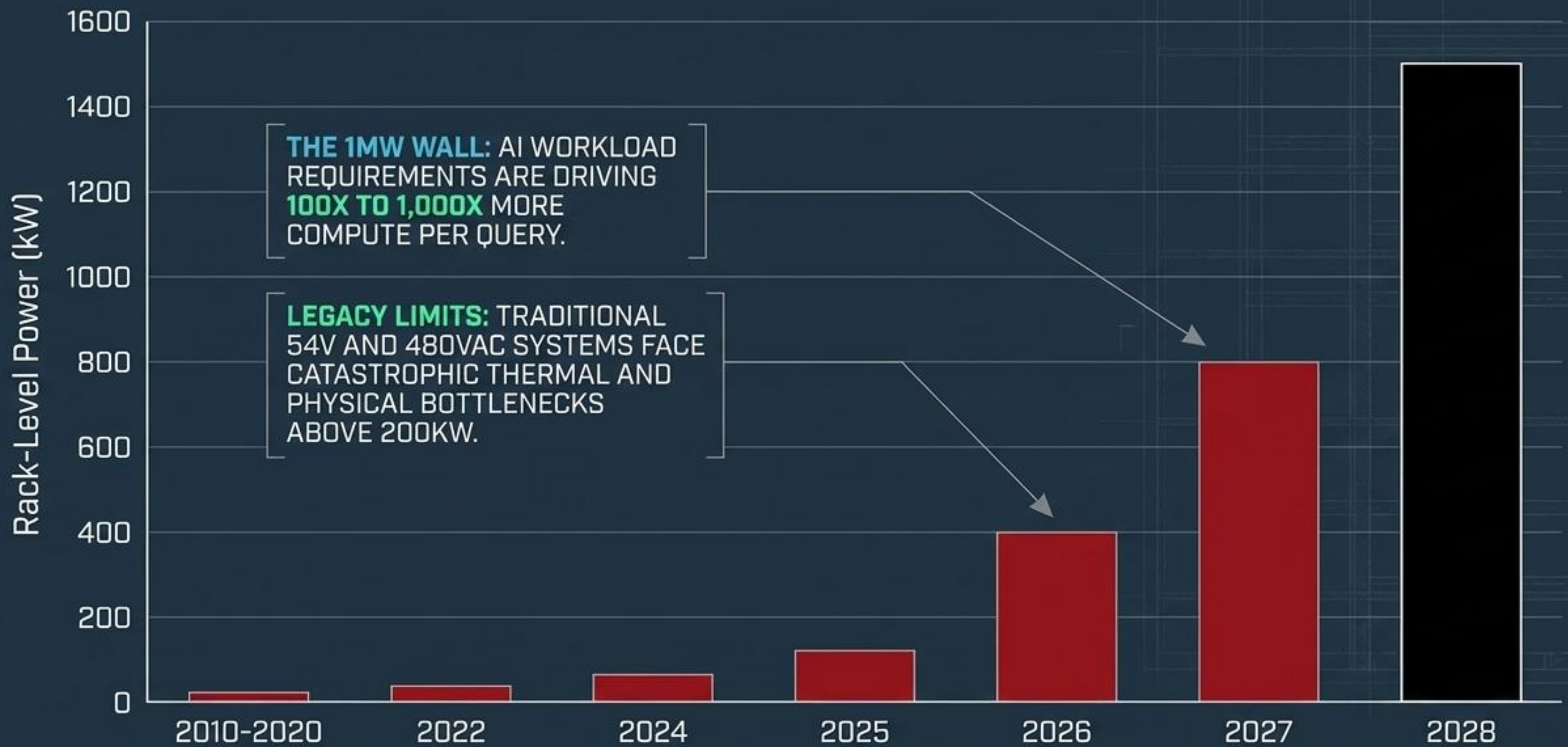
SCALE 1:1

REF. PLAN B1

GRID SYSTEM REV. 12

BL-01
0.0,1080.0

BR-01
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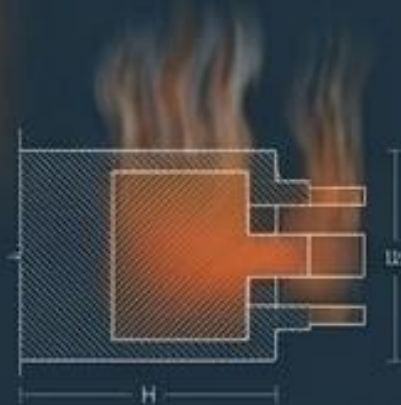
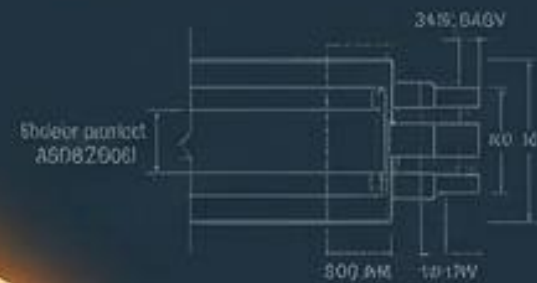
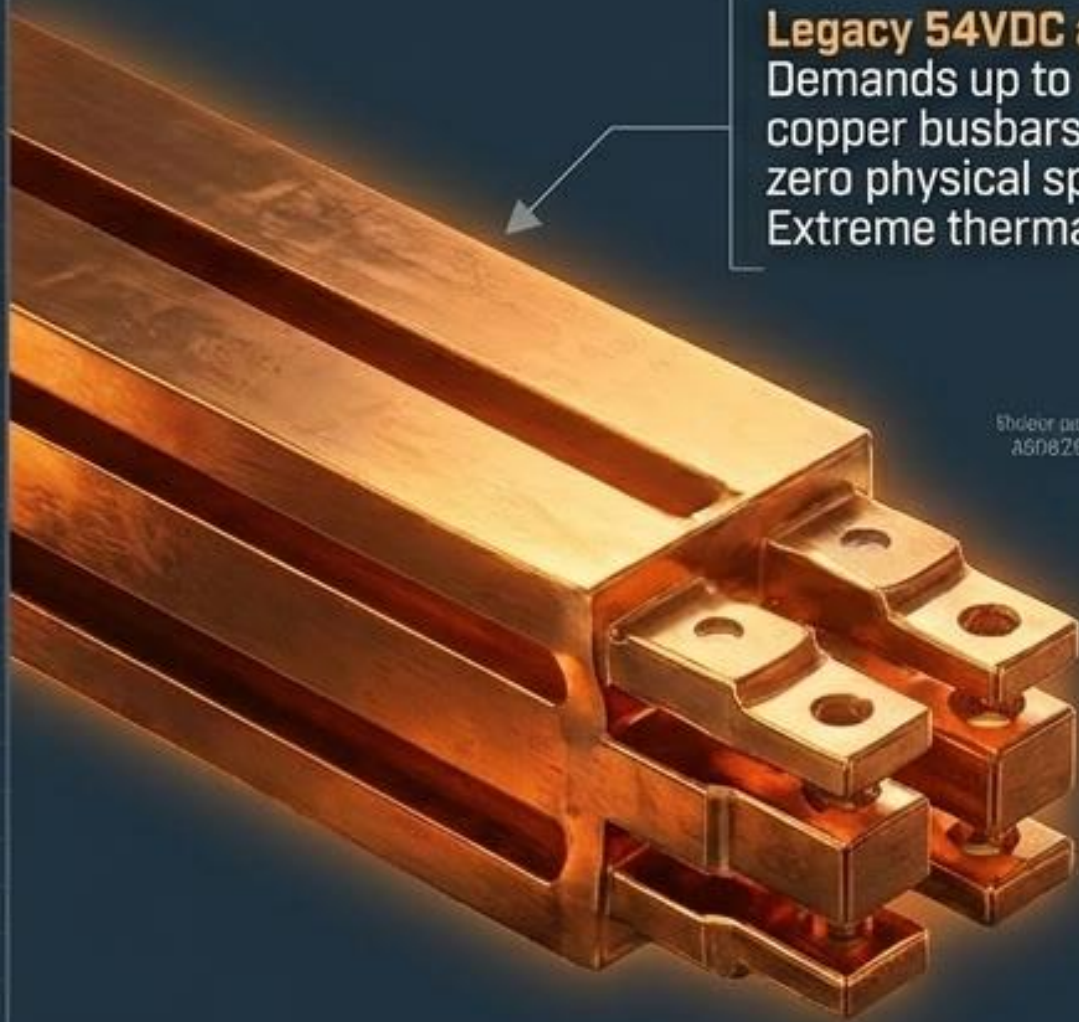


Rack-Level Power Requirements

THE COPPER PARADOX: WHY 54V CANNOT SCALE

Legacy 54VDC at 1MW

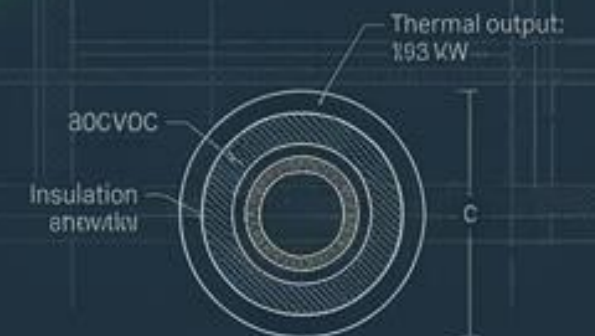
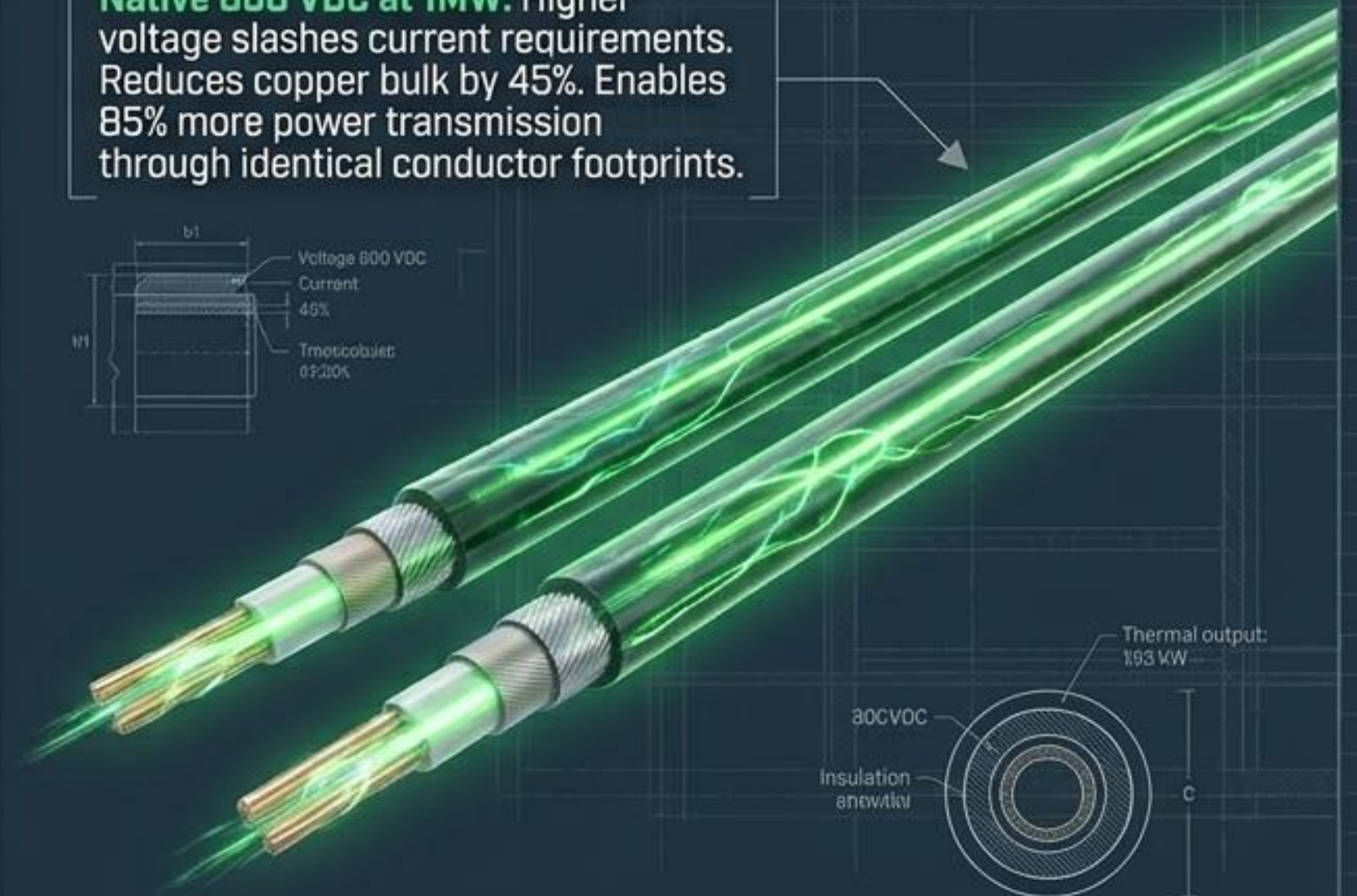
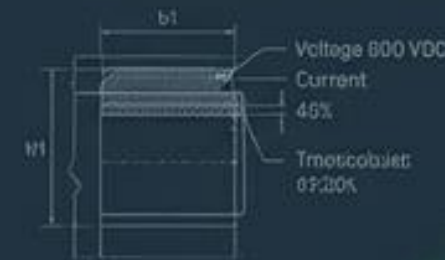
Legacy 54VDC at 1MW: Demands up to 200kg of solid copper busbars per rack. Leaves zero physical space for compute. Extreme thermal penalty.



Legacy 54VDC at 1MW

Native 800 VDC at 1MW

Native 800 VDC at 1MW: Higher voltage slashes current requirements. Reduces copper bulk by 45%. Enables 85% more power transmission through identical conductor footprints.



Native 800 VDC at 1MW

THE GENERATIONAL ARCHITECTURE MATRIX

	Gen 1: Traditional	Gen 2: 54VDC Bus	Gen 3 / Next-Gen
Rack Input	277VAC	50VDC	800VDC
AC/DC Conversion	In-Tray PSUs	Power Shelf inside Rack	Moved completely outside to Sidecar/Power Room
UPS/Backup Location	Central Facility UPS	Local BBU in Rack	Hall Sidecar BBU/CBU
Rack Power Ceiling	20kW	~100kW	1MW+

The Paradigm Shift: Native 800 VDC Integration

The Kyber Architecture:

NVIDIA's upcoming rack standard designed natively for 800VDC, launching in 2027.

SPEC: Kyber Std.

The Efficiency Multiplier:

Eliminates redundant in-rack conversions, freeing up 26% more real estate for pure compute.

EFFICIENCY GAIN: +26%

TCO Impact:

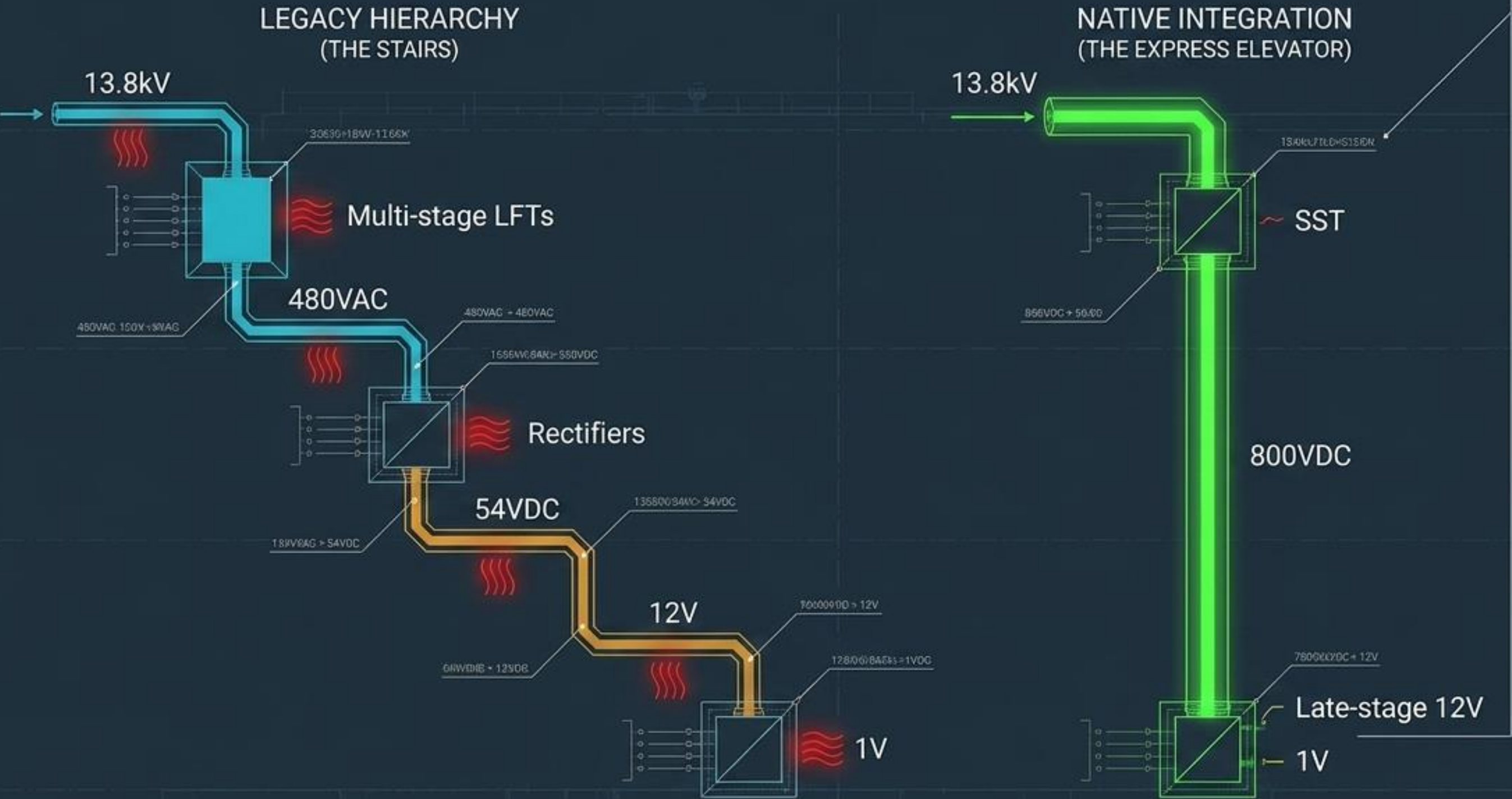
Unlocks sustainable AI factory growth, cutting total cost of ownership by up to 30% through massive efficiency and cooling gains.

Sustainable AI Factory Growth

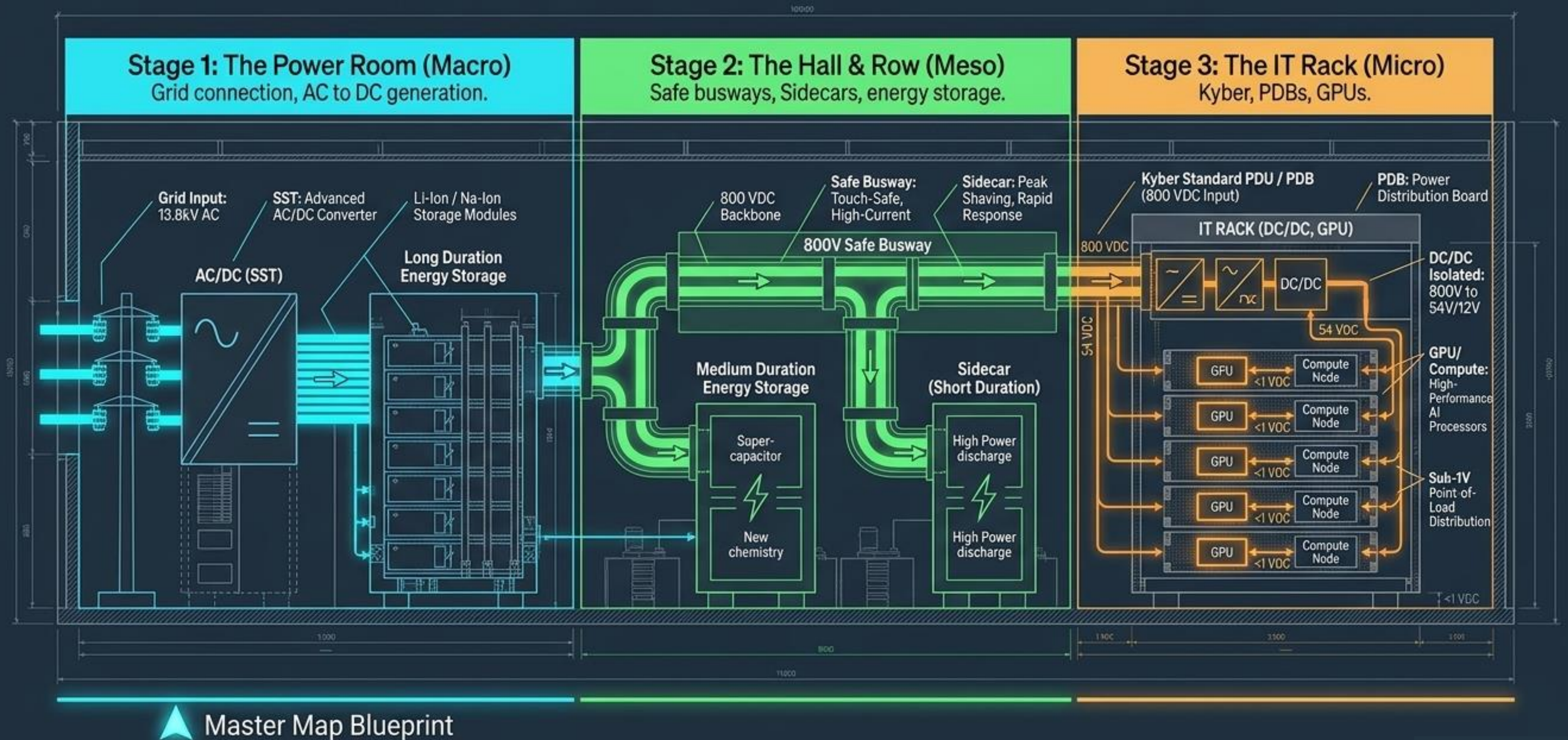


ENERGY DELIVERY COMPARISON: THE ENERGIZED BLUEPRINT

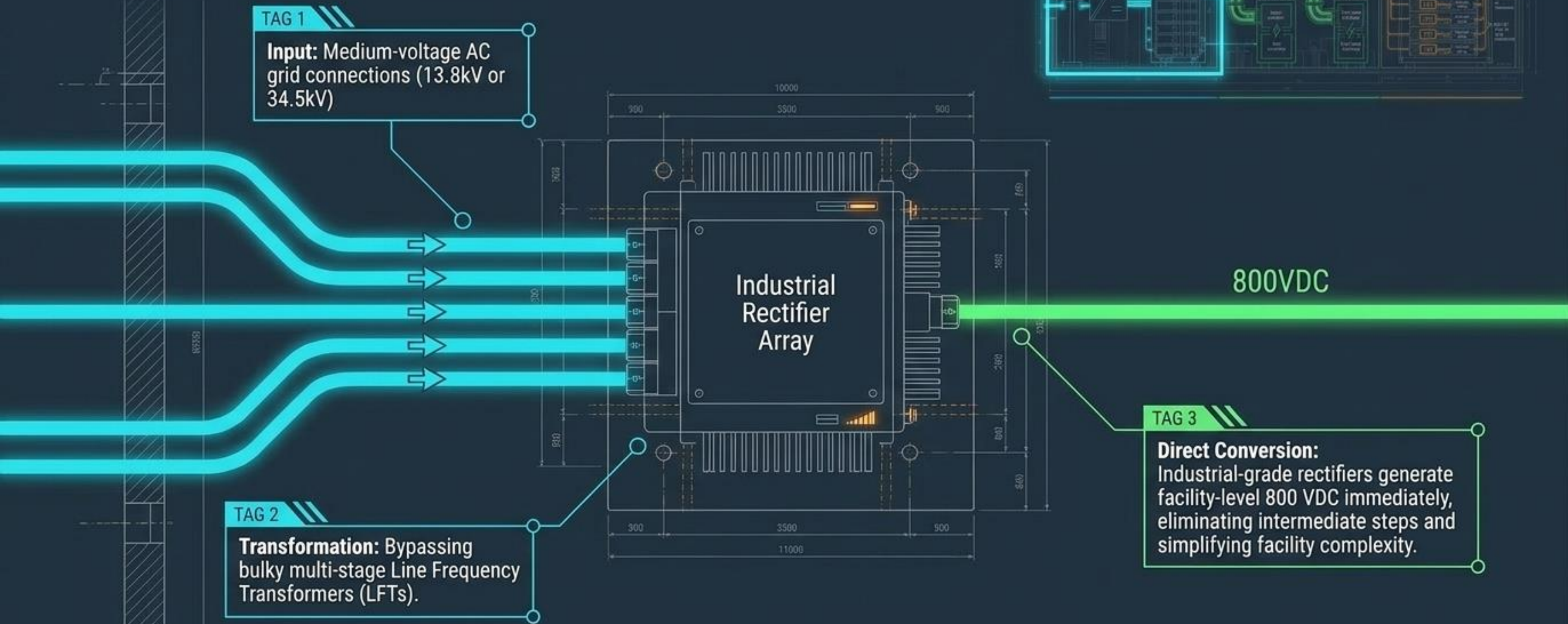
Every AC/DC and DC/DC conversion stage bleeds energy as heat. The 800 VDC architecture bypasses legacy facility transformers and rack-level PSUs, delivering high voltage directly to the compute node.



The Spatial Anatomy of an AI Factory



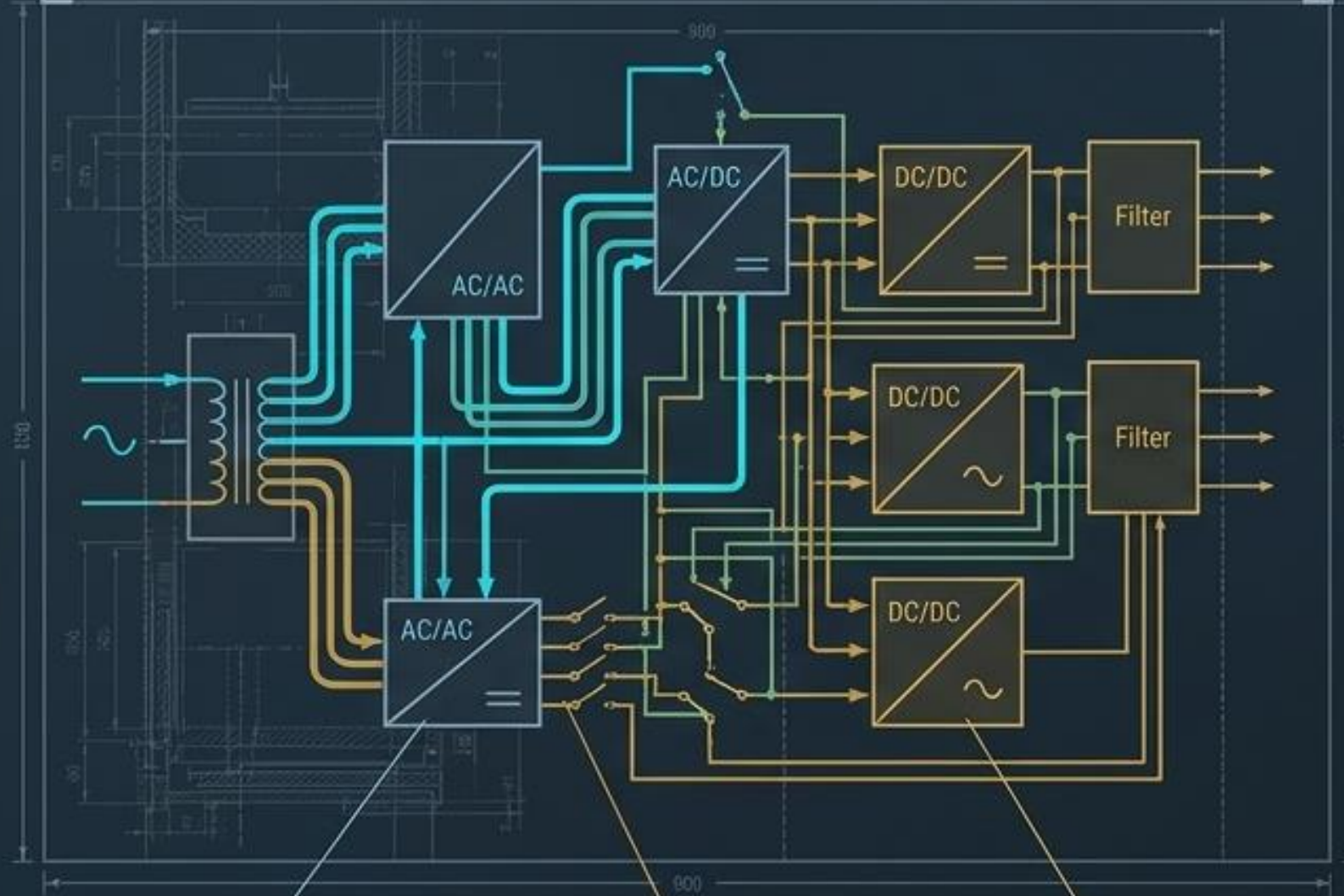
Stage 1: The Power Room



Power Conversion Topology Comparison

Legacy LFT

Line Frequency Transformers + Multi-Stage Rectifiers



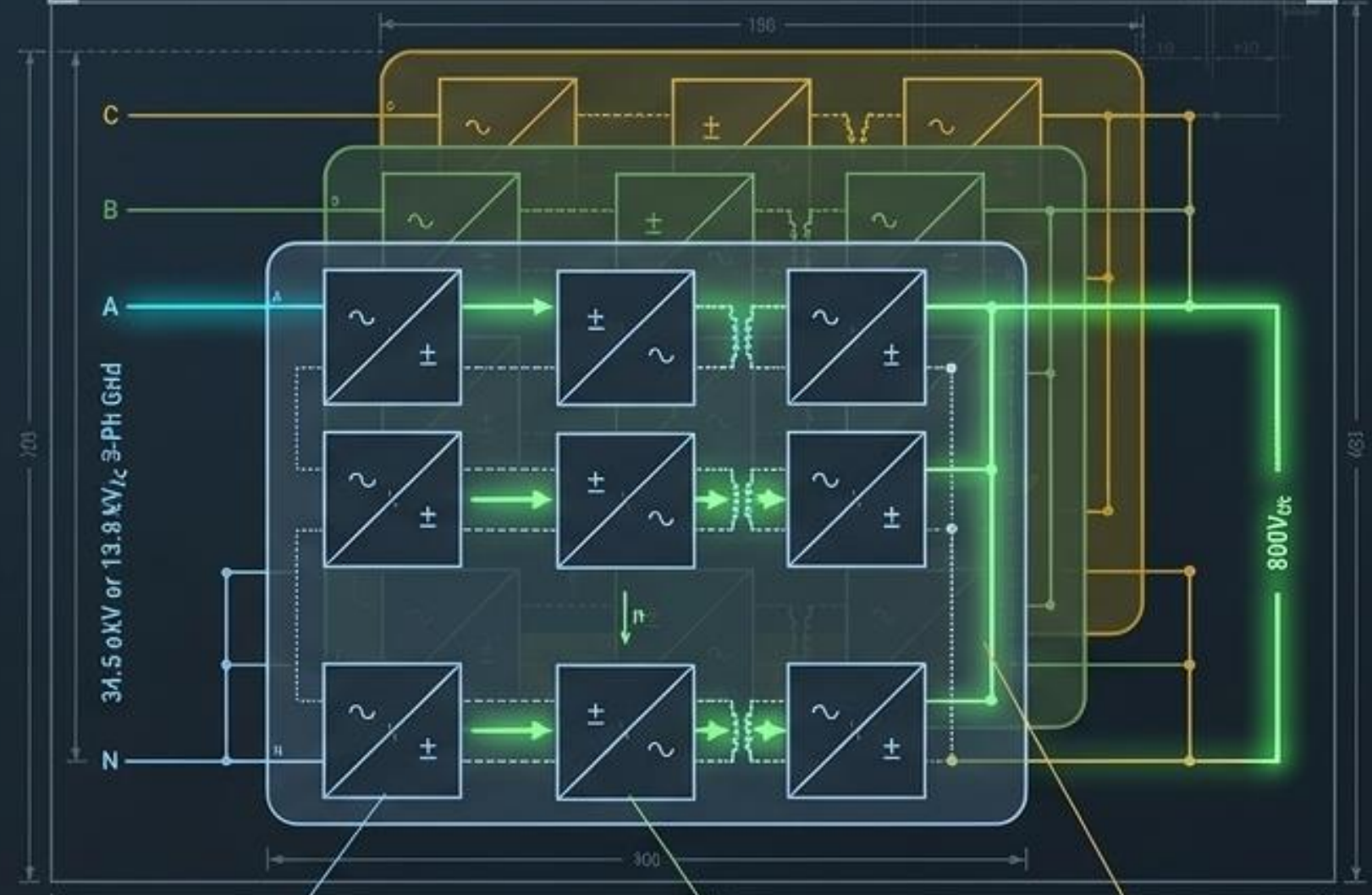
Bulky footprint

Lossy AC distribution

Complex switching

SST with SiC

Solid State Transformers (SST)



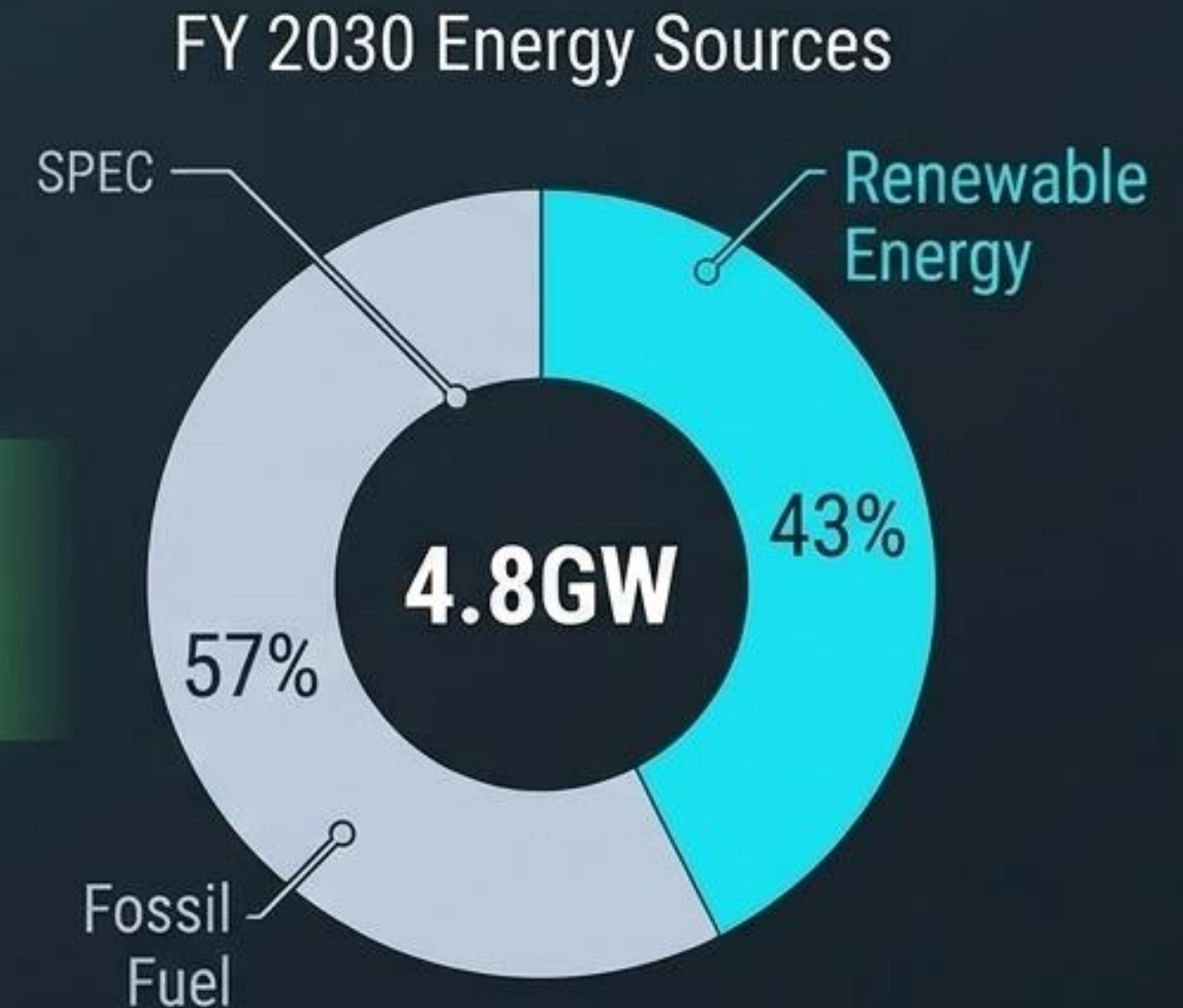
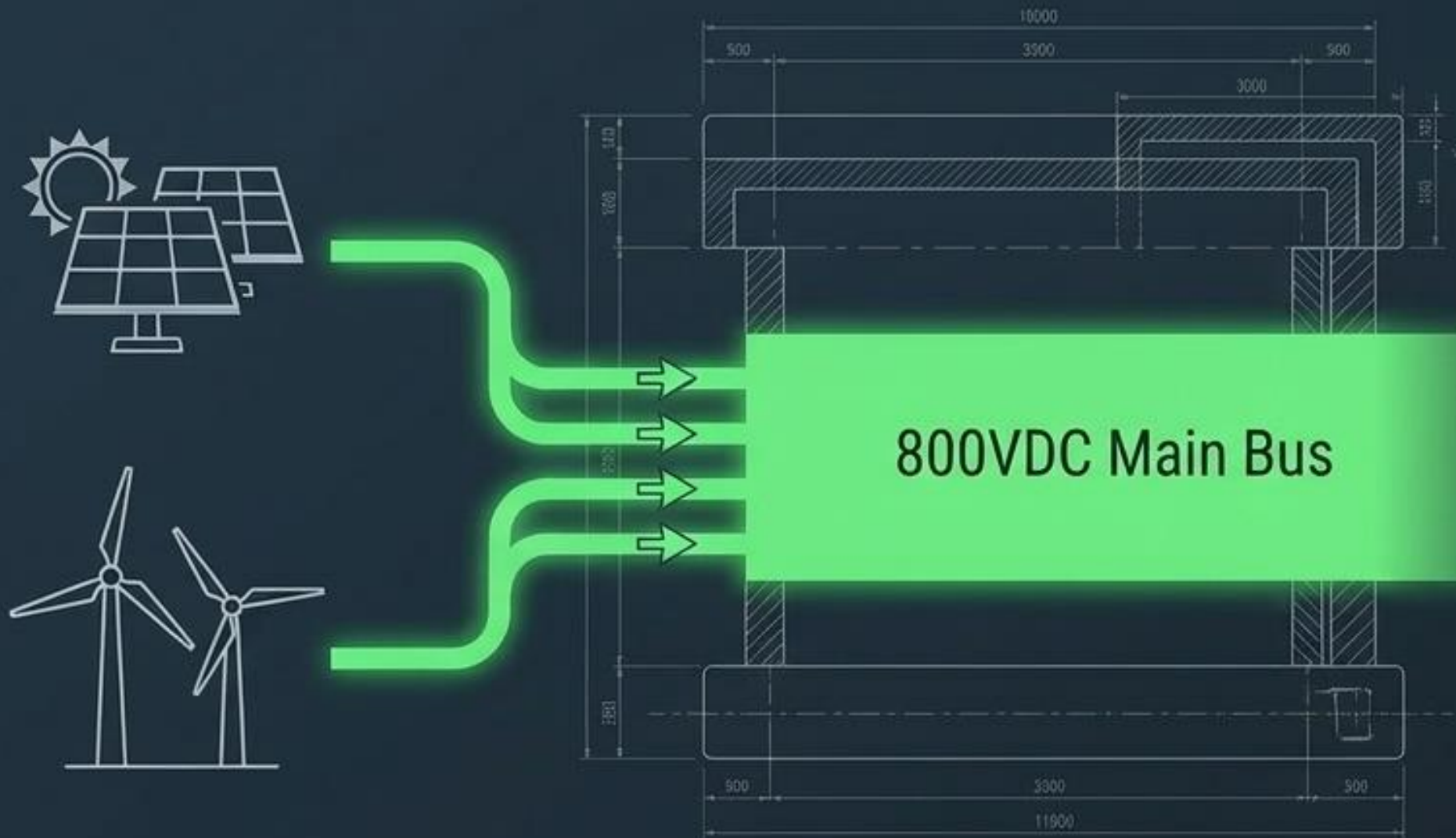
Powered by high-voltage (1200V+) Silicon Carbide (SiC) semiconductors.

Converts 34.5kV/13.8kV directly to 800 VDC.

Minimizes electrical complexity and maintenance.

Global alignment with the IEC's low-voltage DC (LVDC) classification ($\leq 1,500$ VDC)

Native Renewable Integration



TAG 1

The AI power mandate requires a massive shift to renewables (projected 43% of AI energy mix by 2030).

TAG 2

An **800 VDC** grid provides the ideal native framework for direct integration of DC-generating solar and wind resources.

TAG 3

Enhances sustainability while eliminating inverter conversion losses.

Stage 2: The Hall & Row



800VDC SAFE BUSWAY

Transmission: 800V Safe Busway routes direct current safely across the facility.

SIDECAR

The Sidecar: Replaces the legacy in-rack power shelf. Takes 480VAC/800VDC and houses critical energy storage right at the row level.

Scalability: Allows operators to bridge legacy facility infrastructure with forward-looking 1.1 MW in-row power delivery designs.

Sub-Second Load Volatility & Energy Storage



SPEC TAG

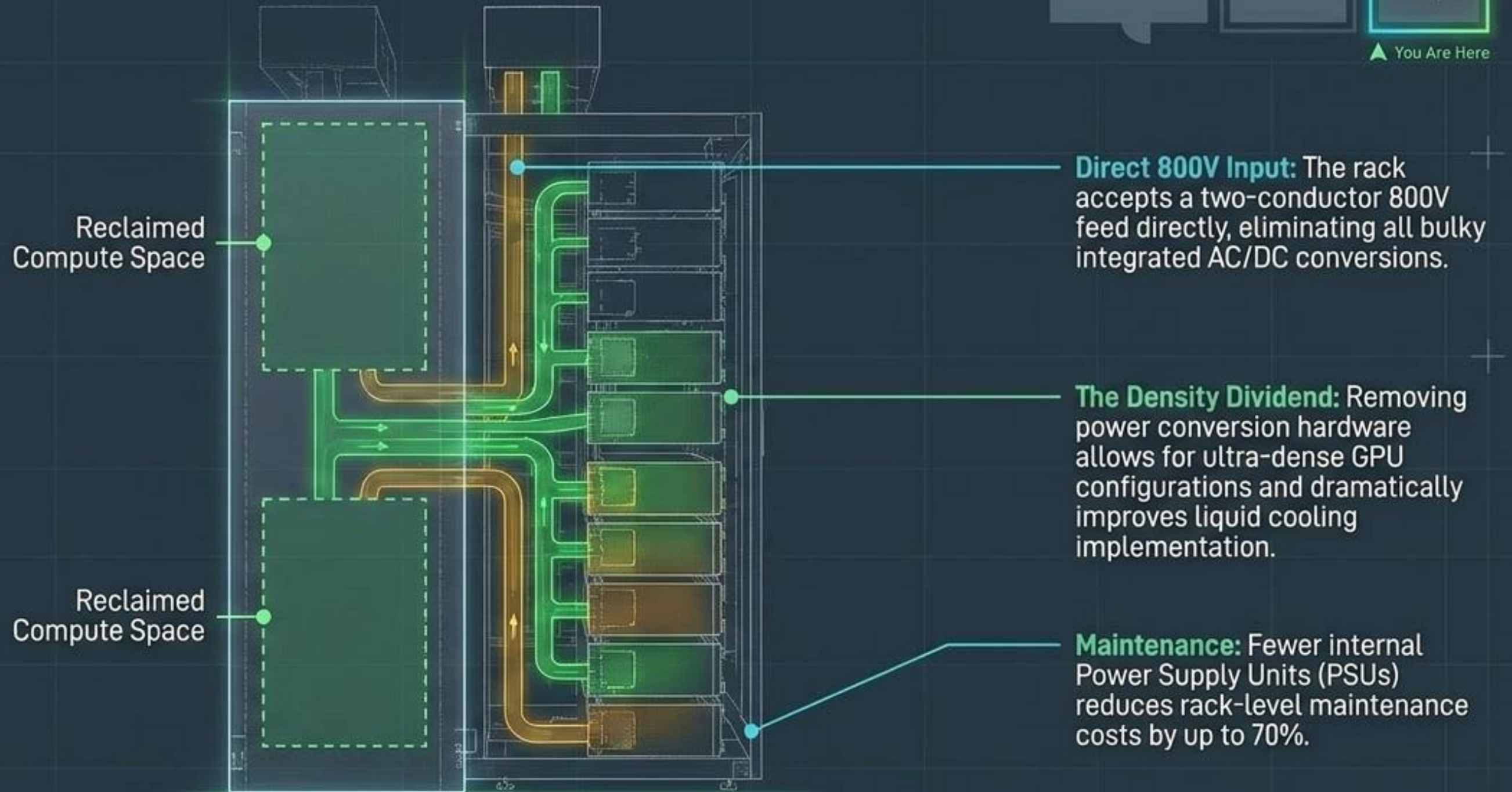
AI compute loads are not static; they exhibit immense, sub-second power fluctuations.

SPEC TAG

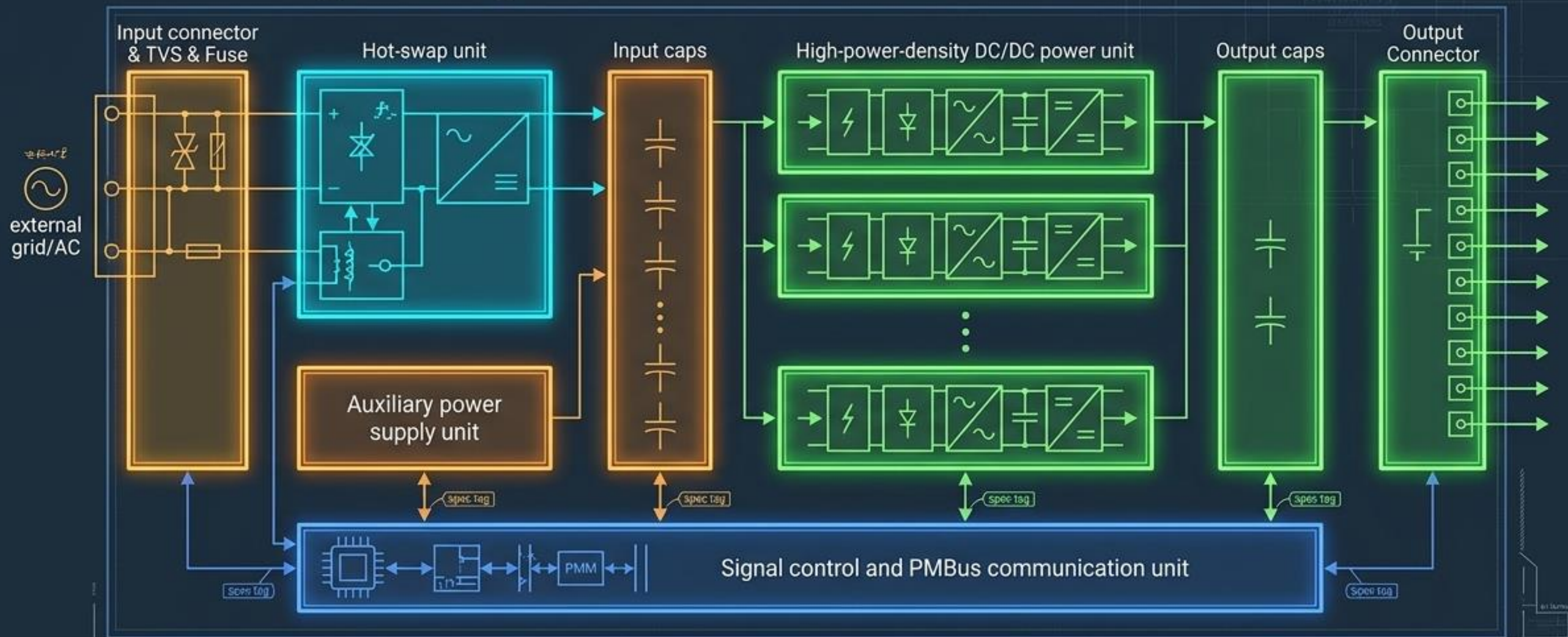
Local Energy Storage: The Sidecar houses Battery Backup Units (BBU) and Capacitor Backup Units (CBU) immediately adjacent to the racks.

The Buffer: These units handle load spikes and prevent extreme voltage transients from crashing the GPUs, replacing slow, centralized facility UPS systems.

Stage 3: The NVIDIA Kyber IT Rack



The PDB: The High-Voltage Critical Hub



Function



Distributes the central high-voltage 800VDC into multiple tailored output channels.

Protection



Integrated input connectors, TVS (Transient Voltage Suppressor), and fuses guard downstream components against overvoltage and overcurrent.

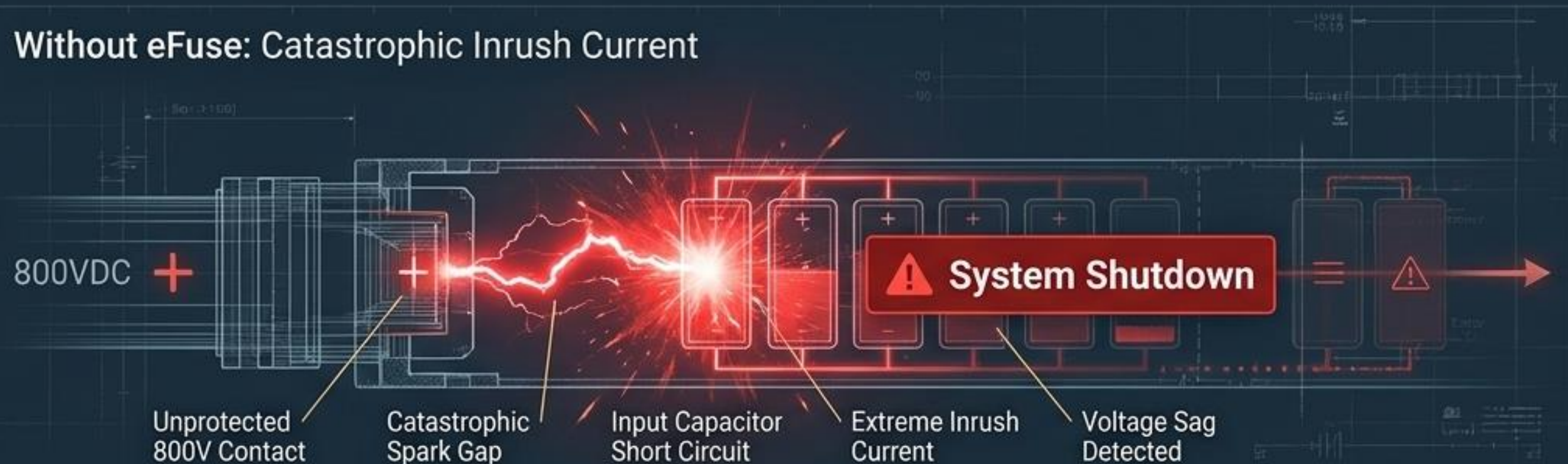
Intelligence



PMBus (Power Management Bus) controls regulation and monitors real-time voltage, current, and thermal telemetry.

Hot-Swap Anatomy & eFuse Technology

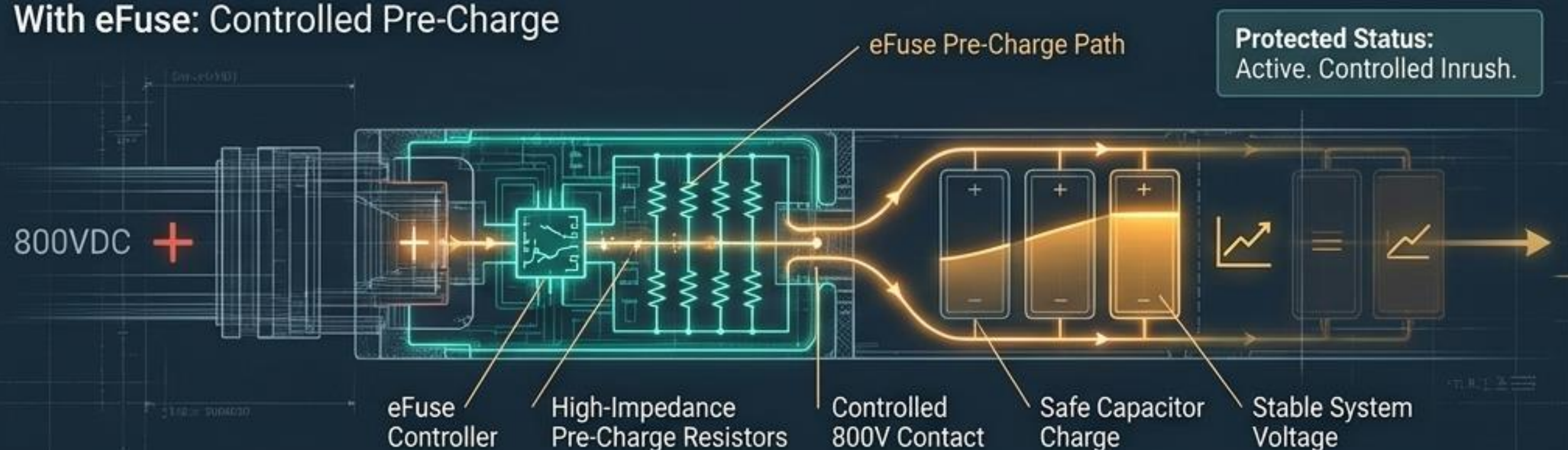
Without eFuse: Catastrophic Inrush Current



The Physics of Insertion: Inserting an uncharged capacitor directly into an 800VDC bus acts as a short circuit, creating an inrush current strong enough to blow fuses and drop system voltage.

The eFuse Solution: Hot-swap controllers use a high-impedance pre-charge path to safely limit inrush current.

With eFuse: Controlled Pre-Charge



Operational Impact: Enables live maintenance of 800V systems without disrupting adjacent server trays. Slashes Mean Time To Repair (MTTR) by 90% (down to 10-15 minutes), preventing tens of thousands of dollars in downtime losses.

The 64:1 LLC Converter Engine

800VDC

12V / 6V Bus

Performance Benchmark:

Achieving peak efficiencies of 97.6% to 98.5% with unprecedented power densities ($>2000\text{W}/\text{in}^3$).

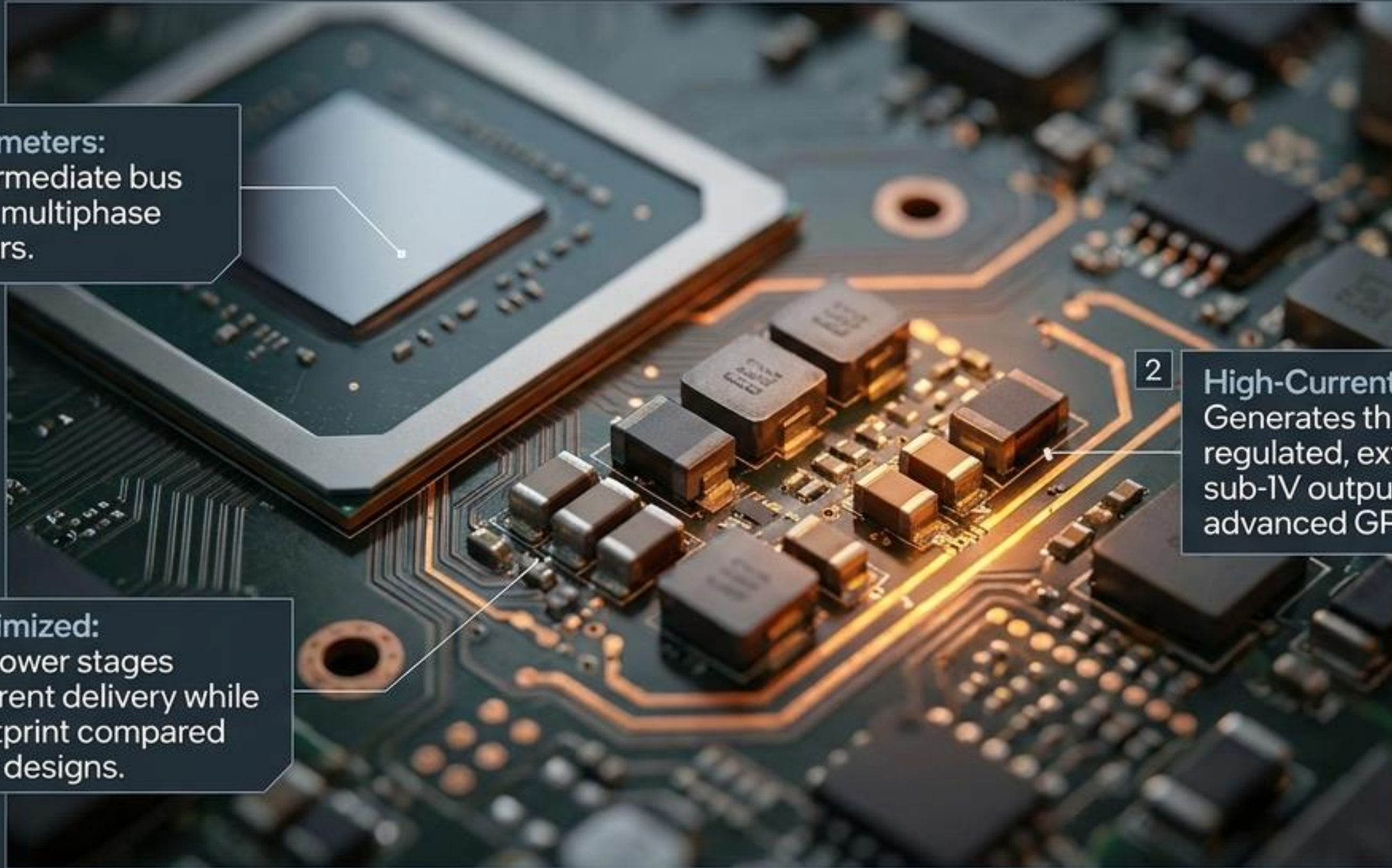
Wide-Bandgap Materials:

Utilizing advanced GaN (Gallium Nitride) and SiC (Silicon Carbide) power stages.

The Final Step-Down:

Late-stage, high-ratio 64:1 isolated LLC converters take the 800V input and drop it precisely to an intermediate 54V, 12V, or 6V bus.

Point of Load: Driving the AI Core



1

The Final Millimeters:
6V or 12V intermediate bus
is delivered to multiphase
buck converters.

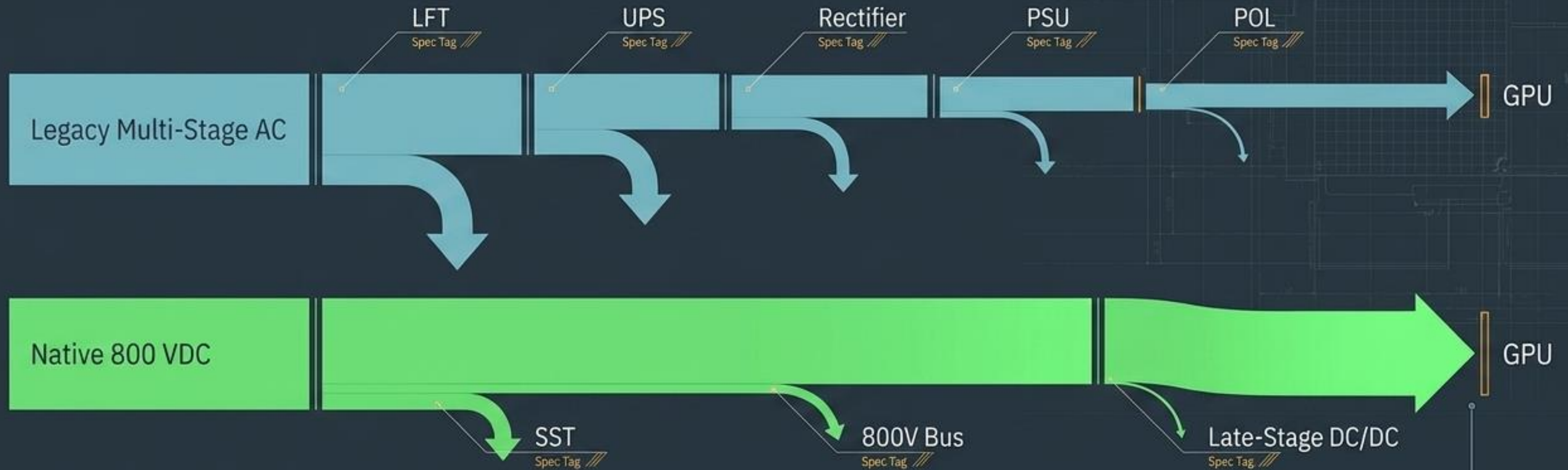
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High-Current Delivery:
Generates the highly
regulated, extreme-current,
sub-1V outputs required by
advanced GPU cores.

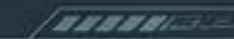
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Spatially Optimized:
Dual-phase power stages
maximize current delivery while
shrinking footprint compared
to legacy 12V designs.

The Power Density Waterfall



By eliminating redundant AC/DC and DC/DC conversion stages, the native 800 VDC architecture improves total end-to-end efficiency by up to 5%, maximizing AI tokens generated per watt.



A Unified Industry Ecosystem

ROHM Semiconductor
SiC devices enabling high-frequency power switching and renewable grid integration.



Delta Electronics
High-efficiency Hot-Swap PDBs and core-shell liquid-cooled busbars.



Navitas Semiconductor
Ultra-high voltage SiC for SST grid connections and GaN DC-DC bricks.

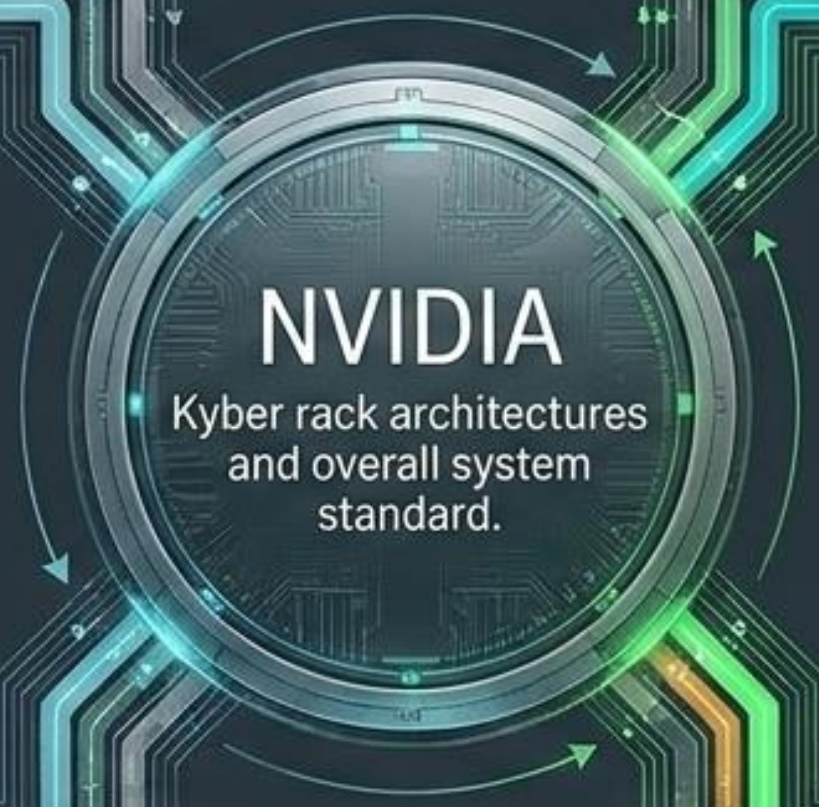


Texas Instruments
800V hot-swap controllers and high-density 800V-to-6V GaN power stages.

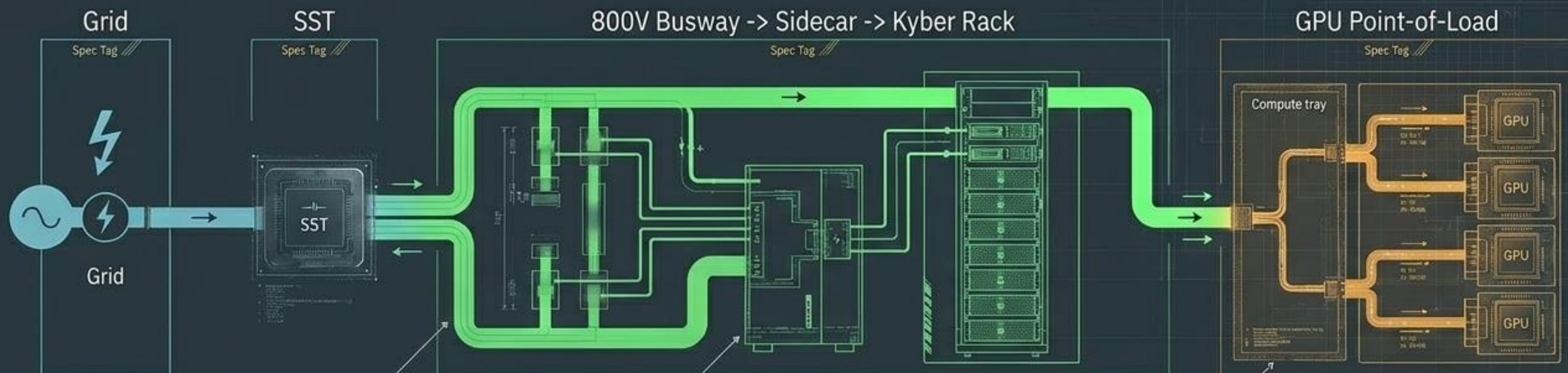


NVIDIA

Kyber rack architectures
and overall system
standard.



The 1MW AI Factory Blueprint



**Spatial
Un-bottlenecking:**
Moving AC/DC out of the
rack reclaims space for
pure compute density.

**Thermal
Un-bottlenecking:**
Reducing conversion
stages dramatically lowers
ambient facility heat.

**Token
Un-bottlenecking:**
Maximum power delivered
directly to the GPU core at
5% higher end-to-end
efficiency.

The Bottom Line:
800 VDC is not just a
voltage upgrade; it is the
fundamental physical
prerequisite for the future
of artificial intelligence.